WHAT IS CLAIMED IS:

1. A method of remediating PCB contamination on metal surfaces comprising the step of contacting said metal surface with a pollution remedial composition comprising:

more than 35 volume percent but less than 40 volume percent of a soluble silicate;

from about 0.25 to about .5 volume percent of a surfactant;

from about .5 to about 5 volume percent of a polyol; and

the remainder water.

2. The method of Claim 1, including

contacting said metal surface with said pollution remedial composition by applying said pollution remedial composition to said metal surface.

3. The method of Claim 2, including

applying said pollution remedial composition to said metal surface by painting said pollution remedial composition to said metal surface.

4. The method of Claim 2, including

applying said pollution remedial composition to said metal surface by spraying on said pollution remedial composition to said metal surface.

5. The method of Claim 4, including

power washing said pollution remedial composition onto said metal surface.

6. The method of Claim 1, wherein

said metal surface is coated with a PCB-containing primer.

7. The method of Claim 5, wherein

said metal surface is a section of a ship.

8. The method of Claim 1, wherein

said soluble silicate is sodium silicate.

9. The method of Claim 1, wherein

said surfactant is an ethoxylated nonylphenol containing an average of 9.5 ethyleneoxy units per molecule.

10. The method of Claim 1, wherein

said polyol is a polyethylene glycol.

11. The method of Claim 1, wherein

said soluble silicate is sodium silicate;

said surfactant is an ethoxylated nonylphenol containing an average of 9.5 ethyleneoxy units per molecule; and

said polyol is a polyethylene glycol.

12. The method of Claim 1, wherein

said soluble silicate is about 38.5 volume percent of said composition;

said surfactant is about 4.0 volume percent of said composition;

said polyol is about .5 volume percent of said composition; and

the remainder of said composition is water.